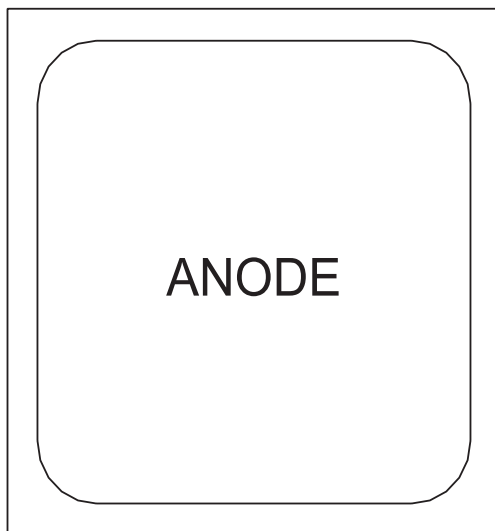


PROCESS DETAILS

Process	GLASS PASSIVATED MESA
Die Size	87 x 87 MILS
Die Thickness	10.4 MILS
Anode Bonding Pad Area	69.5 x 69.5 MILS
Top Side Metalization	Au - 5,000Å
Back Side Metalization	Au - 2,000Å

GEOMETRY



BACKSIDE CATHODE

R0

GROSS DIE PER 4 INCH WAFER

1,490

PRINCIPAL DEVICE TYPES

1N5400 thru 1N5408

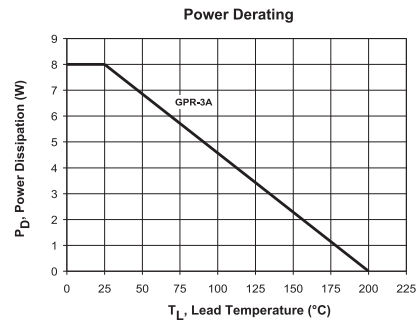
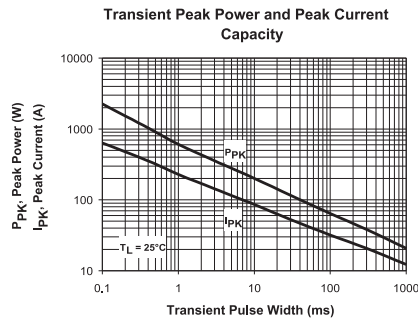
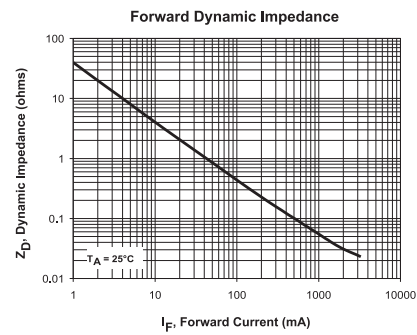
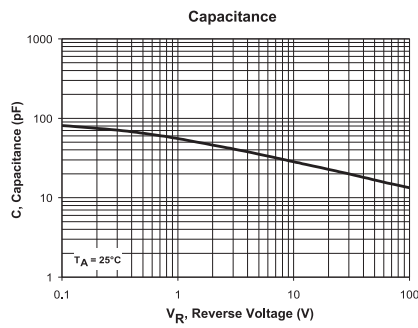
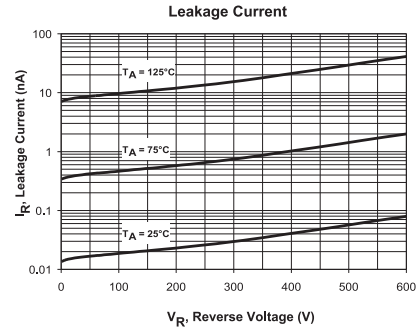
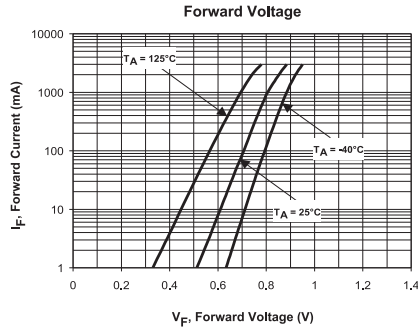
1N5550 thru 1N5554

1N5624 thru 1N5627

CMR3-02 Series

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R2 (16- September 2003)



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